

8-17-98

AUG 17 1998



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To the Honorable Commissioner of Patents and Trademarks, Please record the attached original document or copy thereof.

1. Names of conveying party:

1) ARDESHIR J. SIDHWA
 2) _____
 3) _____
 4) _____
 5) _____
 6) _____

Additional names of conveying parties attached? Yes No

2. Name and address of receiving party:

Name: STMICROELECTRONICS S.R.L.

Internal Address: _____

Street Address: 1310 ELECTRONICS DRIVE

Postal Code & City: CARROLTON, TEXAS 75006-5039

Country USA

Additional names & addresses attached? Yes No

3. Nature of conveyance:

Assignment Merger

Security Agreement Change of Name

Other _____

Execution Dates:

1) AUGUST 7, 1998 4) _____
 2) _____ 5) _____
 3) _____ 6) _____

4. Application number(s) or registration number(s):

If this document is being filed together with a new application, the execution date of the application is _____.

A. Patent Application No(s). _____

B. Patent No(s). _____

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: SEED AND BERRY LLP

Internal Address: DAVID V. CARLSON

6300 COLUMBIA CENTER

Street Address: 701 FIFTH AVENUE

City: SEATTLE State: WA ZIP: 98104-7092

6. Total number of applications and patents involved..... 1

7. Total Fee (37 CFR 3.41): \$40

Enclosed

Authorized to be charged to deposit account

8. Deposit account number: 19-1090

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

DAVID V. CARLSON David V. Carlson August 12, 98
 Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and document: 3

ASSIGNMENT

WHEREAS, I, Ardeshir Sidhwa (hereinafter referred to as ASSIGNOR), having a post office address of 7280 East Desert Vista Road, Scottsdale, Arizona 85255, am the sole inventor of an invention entitled "ELIMINATION OF CRACKS GENERATED AFTER A RAPID THERMAL PROCESS STEP OF A SEMICONDUCTOR WAFER," as described and claimed in the specification for which an application for United States letters patent was filed on February 20, 1998 and assigned Application No. 09/027,357.

WHEREAS, STMicroelectronics Inc. (hereinafter referred to as ASSIGNEE), a corporation of the State of Delaware having a place of business at 1310 Electronics Drive, Carrollton, Texas 75006-5039, is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefor in the United States and in any and all countries of the world;

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR hereby sells, assigns and transfers unto said ASSIGNEE the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all countries of the world, and in any and all divisions, reissues and continuations thereof, including the right to file applications worldwide directly in the name of ASSIGNEE and to claim priority rights deriving from the first filed application to which said worldwide applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR had ASSIGNOR been the original owner and this assignment, transfer and sale not been made. ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR agrees to execute all instruments and documents required for the making and prosecution of applications for United States and

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letters patent in all countries of the world on said invention, for litigation regarding letters patent, or for the purpose of protecting title to said invention or letters patent therefor.

Ardeshir J. Sidhwa
ARDESHIR J. SIDHWA
Date: 08/07/98

I certify that I know or have satisfactory evidence that the above person signed this instrument of his own free will, as a voluntary act for the uses and purposes mentioned in the instrument.

Witness Ken Clark
Date: 8/7/98

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